

AMENDMENTS TO THE SPECIFICATION

On page 2, line 1, please amend the "Cross Reference To Related Applications" as follows.

Cross Reference To Related Applications

This application is a division of serial no. 10/094,161 filed 03/06/2002, Patent No. 6,908,784.

This application is related to serial no. 10/719,907 filed 11/21/2003, Patent No. 7,029,949, to serial no. 10/719,876 filed 11/21/03, Patent No. 6,964,915, to serial no. 11/052,279 filed 02/07/05, ~~to serial no. 11/050,857 filed 02/07/05~~, to serial no. 11/146,397 filed 06/06/2005, Patent No. 7,157,353, to serial no. 11/390,321 filed 03/27/06, to serial no. 11/204,264 filed 08/15/05, to serial no. 11/339,177 filed 01/02/2006, ~~and~~ to serial no. 11/496,180 filed 07/31/2006, and to serial no. 11/052,378, filed 02/07/2005, Patent No. 7,221,059.

In the paragraph on page 23, lines 7-17, (paragraph [0131] of published application) please make the following changes.

In the illustrative embodiment, the circuit side planarization step can be performed such that the thickness of the circuit side polymer layer 36 is reduced by an amount sufficient to expose and planarize the surfaces of the contact bumps 24. In the illustrative embodiment, the planarized circuit side polymer layer 36P ~~24P~~ has a thickness Tcs of about 12 mils (304.8 μm). As another alternative the circuit side planarization step need not also planarize the contact bumps 24. For example, the contact bumps 24 can remain generally concave in shape, and can protrude past the surface of the planarized circuit side polymer layer 36P.